

Product Change Notification - KSRA-08ZQDJ558 (Printer Friendly)

Date:

24 Jan 2018

Product Category:

8-bit PIC Microcontrollers; USB Power Delivery

Notification subject:

CCB 2799 Final Notice: Qualification of CuPdAu bond wire for selected products of 200K wafer technology available in 16L QFN (3x3x0.9mm) package at NSEB assembly site.

Notification text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products of 200K wafer technology available in 16L QFN (3x3x0.9mm) package at NSEB assembly site.

Pre Change:

Using gold (Au) bond wire

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	UTAC Thai Limited (NSEB)	UTAC Thai Limited (NSEB)
Wire material	Au	CuPdAu
Die attach material	8600	8600
Molding compound material	G700LTD	G700LTD
Lead frame material	EFTEC-64T	EFTEC-64T

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

February 24, 2018 (date code: 1808)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	December 2016					→	January 2018					February 2018			
Workweek	49	50	51	52	53		01	02	03	04	05	06	07	08	09
Initial PCN Issue Date			X												
Qual Report Availability										X					
Final PCN Issue Date										X					
Estimated Implementation Date													X		

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

December 27, 2016: Issued initial notification.

January 24, 2018: Issued final notification. Attached the Qualification Report. Provided estimated first ship date on February 24, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-08ZQDJ558_Affected CPN.pdf](#)

[PCN_KSRA-08ZQDJ558_Qual Report.pdf](#)

[PCN_KSRA-08ZQDJ558_Affected CPN.xls](#)

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